REMARKS

Applicants respectfully request favorable reconsideration of this application, as amended.

In the Office Action mailed June 15, 2006, the Examiner objected to the title; rejected Claims 1-5 under 35 U.S.C. § 112, second paragraph, as being indefinite; and rejected Claims 1-5 under 35 U.S.C. § 102(e) as being anticipated by each of U.S. Patent No. 6,815,746 to Suzuki et al. ("*Suzuki*") and U.S. Patent Publication No. 2002/0066956 to Taguchi ("*Taguchi*").

By this Amendment, Applicants have amended the title, amended the specification, and amended Claims 1-5. Claims 1-5 remain pending.

Applicants have amended the title and the specification to address the alleged informalities. Applicants have also amended Claims 1-5 to avoid the alleged indefiniteness under 35 U.S.C. § 112, second paragraph.

Without acceding to the rejections of Claims 1-5 under 35 U.S.C. § 102(e), independent Claim 1 has been amended to clarify the invention intended to be claimed.

As set forth in amended Claim 1, Applicants invention provides a multi-chip module including a plurality of first semiconductor chips, a plurality of bumps, a second semiconductor chip, a plurality of bonding wires, and a

sealing member. The plurality of first semiconductor chips are surface-mounted on a surface of a mounting board to exchange signals with each other, and, as now more particularly set forth, the plurality of bumps electrically couple the plurality of first semiconductor chips with the mounting board. The second semiconductor chip is mounted back-to-back with at least one of the plurality of first semiconductor chips, and, as now more particularly set forth, has a plurality of bonding pads on a front surface, where a majority of the bonding pads are arranged along one side of the second semiconductor chip. The plurality bonding wires couple the bonding pads of the second semiconductor chip with corresponding electrodes formed on the mounting board, and the sealing member encapsulates the plurality of first semiconductor chips, the second semiconductor chip, and the bonding wires, on the mounting board.

Suzuki discloses a plurality of first semiconductor chips 5 and 6 fixed on the main surface of a wiring board 2 with adhesives 13, and a second semiconductor chip 6 adhered to the front surface of one of the semiconductor chips. *Suzuki*, Figures 5 and 6. Suzuki also discloses the front surfaces of all of the semiconductor chips being wire-bonded to the wiring board 2. *Id.* In contrast, Applicants'

amended Claim 1 requires a plurality of bumps that electrically couple the plurality of first semiconductor chips with the mounting board. Moreover, unlike the back-to-front stacking in *Suzuki*, Applicants' invention uses back-to-back stacking of chips. *Suzuki*, therefore, fails to disclose or suggest Applicants' invention as defined in amended Claim 1.

Taguchi suffers similar deficiencies with respect to amended Claim 1 as were discussed above in connection with *Suzuki*.

At least in view of the foregoing, amended independent Claim 1, and its dependent claims, distinguish patentably from the cited references.

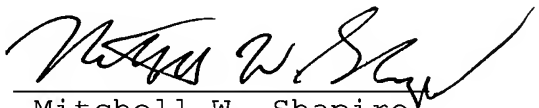
Accordingly, this application is in condition for allowance and should be passed to issue.

The Commissioner is hereby authorized to charge to Deposit Account No. 50-1165 (T3351-8812US01) any fees under 37 C.F.R. §§ 1.16 and 1.17 that may be required by this paper and to credit any overpayment to that Account.

If any extension of time is required in connection with the filing of this paper and has not been separately requested, such extension is hereby requested.

Respectfully submitted,

Date: September 15, 2006

By: 

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